

REMARKS

Claims 1-8 are in this case. Claims 1-6 have been rejected. Claim 1 has been amended to clarify the invention. Claim 7 is added to describe a ceramic substrate formed from organic binder and glass. Supporting matter for these claims is found at page 5, lines 25-26. Claim 8 claims several attenuator circuit topologies and is supported in the Specification at page 4, lines 18-24.

Claim Rejections - 35 U.S.C. 102(b):

Claims 1 and 4 are rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent No. 3,916,264 to Berg et al (hereinafter "Berg"). These rejections are believed inapplicable to the claims as amended.

It is well established that a claimed invention is anticipated by a prior art patent only if the patent discloses each and every limitation of the claim. In the present case, independent amended claims 1 and 4 call for a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package.

There is no comparable disclosure in Berg. Berg does not disclose a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. Therefore Berg does not anticipate claims 1 and 4, or their dependent claims.

Claim Rejections - 35 U.S.C. 102(b):

Claims 1, 4, and 6 are rejected under 35 U.S.C. 102(b) as being anticipated by Japanese patent JP 4-320301 to Sunuhara et al (hereinafter "Sunuhara"). These rejections are believed inapplicable to the claims as amended.

In the present case, independent amended claims 1 and 4 call for a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. There is no comparable disclosure in Sunuhara. Sunuhara does not disclose a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. Therefore Sunuhara does not anticipated claims 1, 4, and 6 or their dependent claims.

Claim Rejections - 35 U.S.C. 102(e):

Claims 1-2, and 4-6 are rejected under 35 U.S.C. 102(e) as being anticipated by to Chiang published as US 2002/005914, now allowed, but not yet issued. These rejections are believed inapplicable to the claims as amended.

In the present case, independent amended claims 1 and 4 call for a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. There is no comparable disclosure in Chiang. Chiang does not disclose a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. Therefore Chiang does not anticipated claims 1 and 4 or their dependent claims.

Claim Rejections - 35 U.S.C. 102(e):

Claims 1, 3 4, and 6 are rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Patent No. 6,311,390, to Abe, et al. These rejections are believed inapplicable to the claims as amended.

In the present case, independent amended claims 1 and 4 call for a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. There is no comparable disclosure in Abe. Abe does not disclose a temperature compensated attenuator device formed in a low

temperature cofired ceramic-metal (LTCC-M) system integrated package. Therefore Abe does not anticipated claims 1 and 4 or their dependent claims.

Claim Rejections - 35 U.S.C. 102(b):

Claims 1, 3 4, and 6 are rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent No. 6,020,808 to Hogge (hereinafter "Hogge"). These rejections are believed inapplicable to the claims as amended.

In the present case, independent amended claims 1 and 4 call for a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. There is no comparable disclosure in Hogge. Hogge does not disclose a temperature compensated attenuator device formed in a low temperature cofired ceramic-metal (LTCC-M) system integrated package. Therefore Hogge does not anticipated claims 1 and 4 or their dependent claims.

It is believed that this case now fully complies with 35 U.S.C. §102 and is condition for allowance. Reconsideration and favorable action in this regard are therefore earnestly solicited.

Respectfully submitted,



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AMENDED CLAIMS SHOWING CHANGES

Claim 1:

1. A temperature compensated attenuator device [for compensating] to compensate the effect of temperature changes in an [electrical or] electronic circuit comprising:

a low temperature co-fired ceramic-metal (LTCC-M) integrated package including
a plurality of layers of thermistors [electronically connected in a temperature compensating circuit wherein:] and insulators, at least one of the thermistors [is a sheet thermistor] comprising a sheet of thermistor material having a pair of major surfaces and a pair of electrodes formed on and laterally spaced apart on by the major surfaces, the thermistor sheets layered with insulating layers and electrically connected to form
the attenuator device.